

Layer Stack Up Detail for: PMP7935_REVA.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	2.8mil	FR-4
MidLayer1	(.G1)	1.4mil	FR-4
MidLayer2	(.G2)	1.4mil	FR-4
Bottom Layer	(.GBL)	2.8mil	FR-4
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
 2500MIL X 2500MIL

Number of Layers : 4
 MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 8 MIL
 MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- .5 MIL HOLES +/- .3 MIL

MATERIAL:
 FR-4 FR-4 High Tg OTHER _____

THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENG)
 IMM. TIN/SILVER OR EQUIV OTHER _____

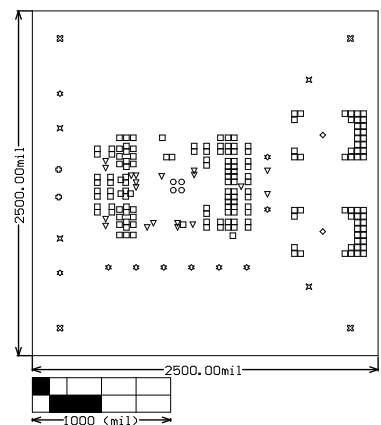
ARRAY/PANEL: CUT AND TRM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S MARKING: RAL METAL SILK

Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	19	10mil (0.254mm)	PTH	Round
□	167	16mil (0.406mm)	PTH	Round
○	4	20mil (0.508mm)	PTH	Round
☆	10	40mil (1.016mm)	PTH	Round
◇	2	51.181mil (1.3mm)	PTH	Round
×	4	98.425mil (2.5mm)	PTH	Round
⊗	4	125.984mil (3.2mm)	PTH	Round
◇	2	188mil (4.725mm)	PTH	Round
	212 Total			

Drill Table



ALL ARTWORK VIEWED FROM TOP SIDE
 BOARD #: PMP7935 REU: B SUN REV: Not In Version Control
 LAYER NAME = 060204-01-01-01-01
 PLOT NAME = Fabrication Drawing
 GENERATED : 4/25/2013 1:09:11 PM TEXAS INSTRUMENTS

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ENGINEER: Robert Sheehan LAYOUT BY: Robert Sheehan
 SCALE: 1.00 ALTUM DESIGNER VERSION: 10.0.0.26245

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